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WO 03/033208 A1

(54) Title: ASSEMBLY SYSTEM FOR STATIONING SEMICONDUCTOR WAFER AND PROCESS FOR MANUFACTURING SEMICONDUCTOR WAFER

(57) Abstract: Disclosed is an assembly system for stationing a semiconductor wafer suitable for processing said wafer, said system comprising: (a) a holding block; (b) a semiconductor wafer; and (c) an aqueous adhesive composition interposed between said ceramic block and said semiconductor wafer, said adhesive composition comprising water; at least one release agent and at least one resin wherein said adhesive composition adheres more strongly to said holding block than to said semiconductor wafer. Also disclosed is a process for manufacturing a semiconductor wafer, comprising the steps of: (a) providing a holding block; (b) providing a semiconductor wafer; (c) coating said holding block or one side of said semiconductor wafer with the foregoing aqueous adhesive composition; (d) contacting one side of said semiconductor wafer to said coated holding block or said coated side of said semiconductor wafer to said holding block; (e) polishing the other side of said semiconductor wafer; and (f) removing the semiconductor wafer from the coated ceramic holding block.